

EMD6 / UMD6N / IMD6A

NPN + PNP Complex Digital Transistors (Bias Resistor Built-in Transistors) Datasheet

<For DTr1(NPN)>

Parameter	Value
V _{CEO}	50V
Ι _C	100mA
R ₁	4.7kΩ

<For DTr2(PNP)>

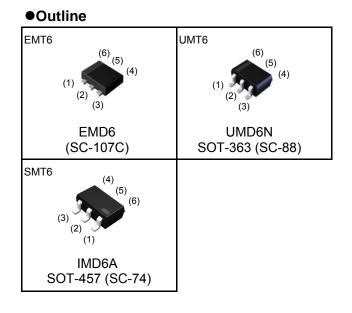
Parameter	Value
V _{CEO}	-50V
I _C	-100mA
R ₁	4.7kΩ

Features

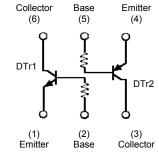
- 1) Both the DTC143T chip and DTA143T chip in one package.
- Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see inner circuit).
- 3) The bias resistors consist of thin-film resistors with complete isolation to allow negative biasing of the input. They also have the advantage of completely eliminating parasitic effects.
- 4) Only the on/off conditions need to be set for operation, making the circuit design easy.
- 5) Lead Free/RoHS Compliant.

Application

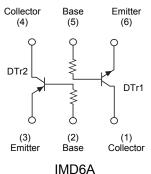
Inverter circuit, Interface circuit, Driver circuit



Inner circuit



EMD6 / UMD6N



I

Part No.	Package	Package size (mm)	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit (pcs)	Marking
EMD6	EMT6	1616	T2R	180	8	8,000	D6
UMD6N	UMT6	2021	TR	180	8	3,000	D6
IMD6A	SMT6	2928	T108	180	8	3,000	D6

Packaging specifications

•Absolute maximum ratings (Ta = 25°C)

Paramete	er	Symbol	DTr1(NPN)	DTr2(PNP)	Unit
Collector-base voltage		V _{CBO}	50	-50	V
Collector-emitter voltage		V _{CEO}	50	-50	V
Emitter-base voltage		V _{EBO}	5	-5	V
Collector current		Ι _C	100	-100	mA
Collector Dower dissinction	EMD6 / UMD6N	P _C ^{*2}	150 (Total) ^{*3}		mW
Collector Power dissipation IMD6A		Γ _C	300 (Total) ^{*4}		mW
Junction temperature		Tj	150		°C
Range of storage temperature	re	T _{stg}	–55 to	o +150	°C

●Electrical characteristics(Ta = 25°C) <For DTr1(NPN)>

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Collector-base breakdown voltage	BV _{CBO}	I _C = 50μA	50	-	-	
Collector-emitter breakdown voltage	BV _{CEO}	I _C = 1mA	50	-	-	V
Emitter-base breakdown voltage	BV _{EBO}	I _E = 50μA	5	-	-	
Collector cut-off current	I _{CBO}	V _{CB} = 50V	-	-	500	nA
Emitter cut-off current	I _{EBO}	V _{EB} = 4V	-	-	500	nA
Collector-emitter saturation voltage	V _{CE(sat)}	I _C / I _B = 5mA / 0.25mA	-	-	300	mV
DC current gain	h _{FE}	V _{CE} = 5V, I _C = 1mA	100	300	600	-
Input resistance	R ₁	-	3.29	4.7	6.11	-
Transition frequency	f _T *1	V _{CE} = 10V, I _E = -5mA f = 100MHz	-	250	-	MHz

•Electrical characteristics(Ta = 25°C) <For DTr2(PNP)>

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Collector-base breakdown voltage	BV _{CBO}	I _C = -50μA	-50	-	-	
Collector-emitter breakdown voltage	BV _{CEO}	I _C = -1mA	-50	-	-	V
Emitter-base breakdown voltage	BV _{EBO}	I _E = -50μA	-5	-	-	
Collector cut-off current	I _{CBO}	V _{CB} = -50V	-	-	-500	nA
Emitter cut-off current	I _{EBO}	V _{EB} = -4V	-	-	-500	nA
Collector-emitter saturation voltage	V _{CE(sat)}	I _C / I _B = -5mA / -0.25mA	-	-	-300	mV
DC current gain	h _{FE}	V_{CE} = -5V, I_{C} = -1mA	100	300	600	-
Input resistance	R ₁	-	3.29	4.7	6.11	-
Transition frequency	f _T *1	V _{CE} = -10V, I _E = 5mA f = 100MHz	-	250	-	MHz

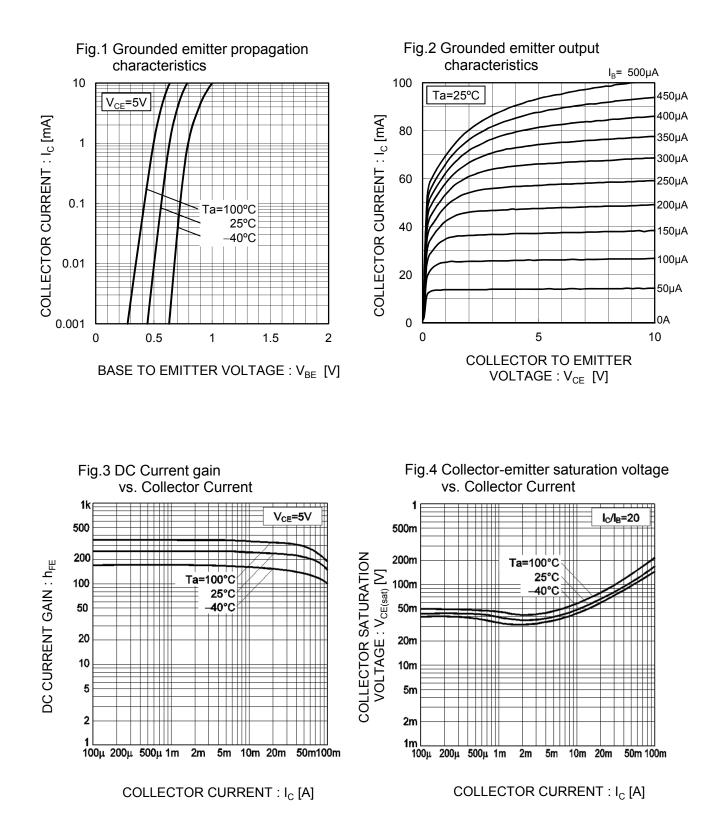
*1 Characteristics of built-in transistor

*2 Each terminal mounted on a reference footprint

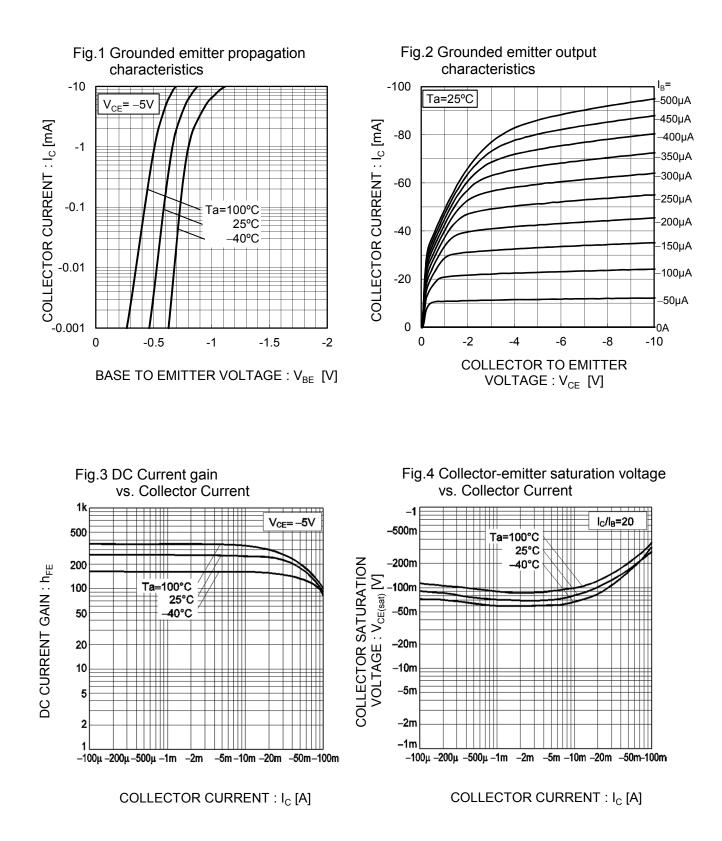
*3 120mW per element must not be exceeded.

*4 200mW per element must not be exceeded.

•Electrical characteristic curves(Ta = 25°C) <For DTr1(NPN)>

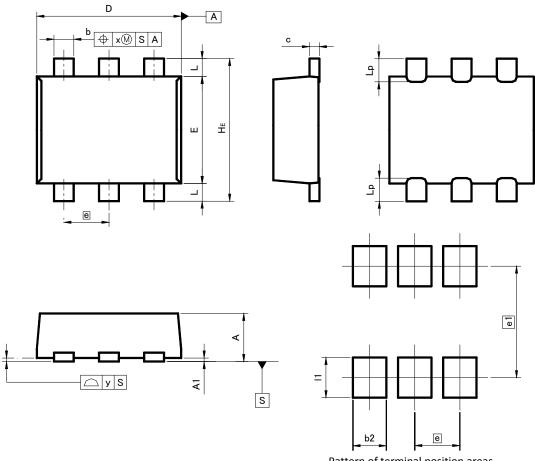


•Electrical characteristic curves(Ta = 25°C) <For DTr2(PNP)>



•Dimensions (Unit : mm)

EMT6



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

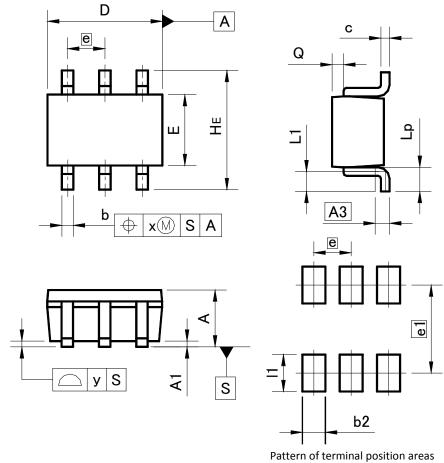
DIM	DIM		INC	HES	
DIM	MIN	MAX	MIN	MAX	
А	0.45	0.55	0.018	0.022	
A1	0.00	0.10	0.000	0.004	
b	0.17	0.27	0.007	0.011	
С	0.08	0.18	0.003	0.007	
D	1.50	1.70	0.059	0.067	
Е	1.10	1.30	0.043	0.051	
е	0.	50	0.020		
HE	1.50	1.70	0.059	0.067	
L	0.10	0.30	0.004	0.012	
Lp	_	0.35	_	0.014	
х	_	0.10	_	0.004	
У	_	0.10	_	0.004	

DIM	MILIMETERS		INC	HES
DIN	MIN	MAX	MIN	MAX
b2	-	0.37	-	0.015
e1	1.25		0.0	49
1	-	0.45	-	0.018

Dimension in mm / inches

•Dimensions (Unit : mm)

UMT6



Pattern of terminal position areas [Not a recommended pattern of soldering pads]

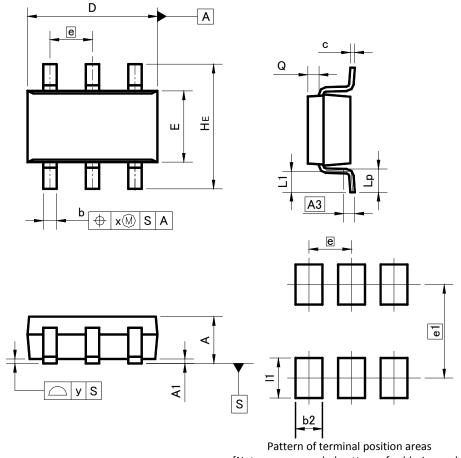
DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
А	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.	25	0.0	10
b	0.15	0.30	0.006	0.012
С	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.	65	0.026	
HE	2.00	2.20	0.079	0.087
L1	0.20	0.50	0.008	0.020
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
х	_	0.10	_	0.004
У	_	0.10	_	0.004

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
b2	-	0.40	-	0.016
e1	1.55		0.0	61
1	-	0.65	-	0.026

Dimension in mm / inches

•Dimensions (Unit : mm)

SMT6



[Not a recommended pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
А	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.2	25	0.0	10
b	0.25	0.40	0.010	0.016
с	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.9	95	0.037	
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
x	_	0.20	-	0.008
У	_	0.10	-	0.004

DIM	MILIMETERS		MILIMETERS		INC	HES
DIN	MIN	MAX	MIN	MAX		
b2		0.60	-	0.024		
e1	2.10		0.0	83		
1	—	0.90	-	0.035		

Dimension in mm / inches

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